

**Gate resistor installed  
Dual N-channel MOSFET**

**KFC4B22670L  
Data Sheet**

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### 1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET  
For lithium-ion secondary battery protection circuits

### 2. FEATURES

- Source-source ON resistance:  $R_{ss(on)}$  typ. = 38 mΩ (VGS = 3.7 V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

### 3. MARKING SYMBOL: 6E

### 4. PACKAGING

Embossed type (Thermo-compression sealing): 20,000 pcs / reel (standard)

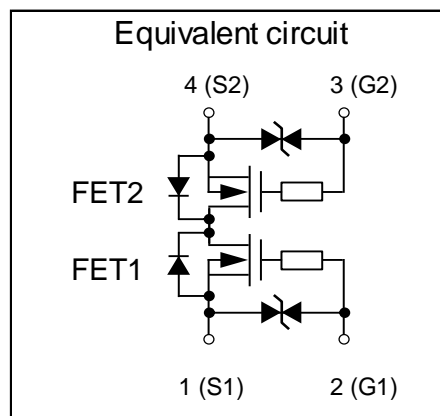
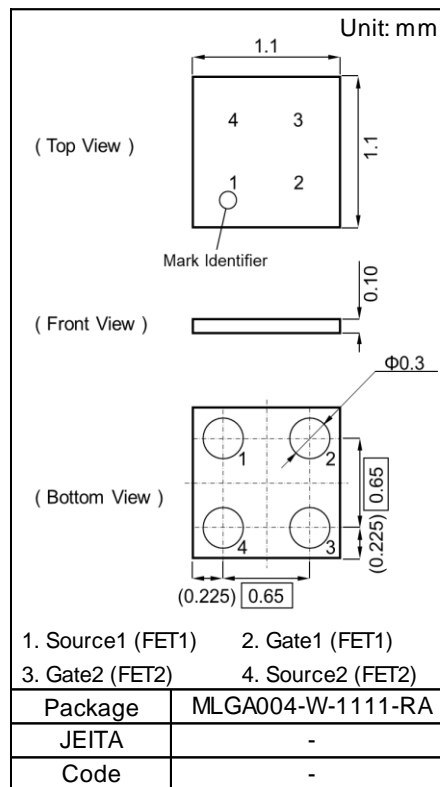
### 5. ABSOLUTE MAXIMUM RATINGS $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	20	V
Gate-source Voltage	VGS	±12	V
Source Current	DC	IS1 <sup>*1</sup>	2.9
		IS2 <sup>*2</sup>	4.6
		IS3 <sup>*3</sup>	6.1
	Pulsed <sup>*4</sup>	ISp	29
Total Power Dissipation	DC	PD1 <sup>*1</sup>	0.42
		PD2 <sup>*2</sup>	1.1
		PD3 <sup>*3</sup>	1.9
Channel Temperature	Tch	150	°C
Storage Temperature Range	Tstg	-55 to +150	°C

### 6. THERMAL CHARACTERISTICS $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth1 <sup>*1</sup>	292	°C / W
	Rth2 <sup>*2</sup>	113	
	Rth3 <sup>*3</sup>	66	

- Note
- \*1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm), FR4 board partially covered with copper pad (18 mm<sup>2</sup> area, 36 μm thickness).
  - \*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm), FR4 board fully covered with copper pad (608 mm<sup>2</sup> area, 36 μm thickness).
  - \*3 Mounted on Ceramic board (70 mm x 70 mm x t1.0 mm).
  - \*4 t = 10 μs, Duty Cycle ≤ 1 %



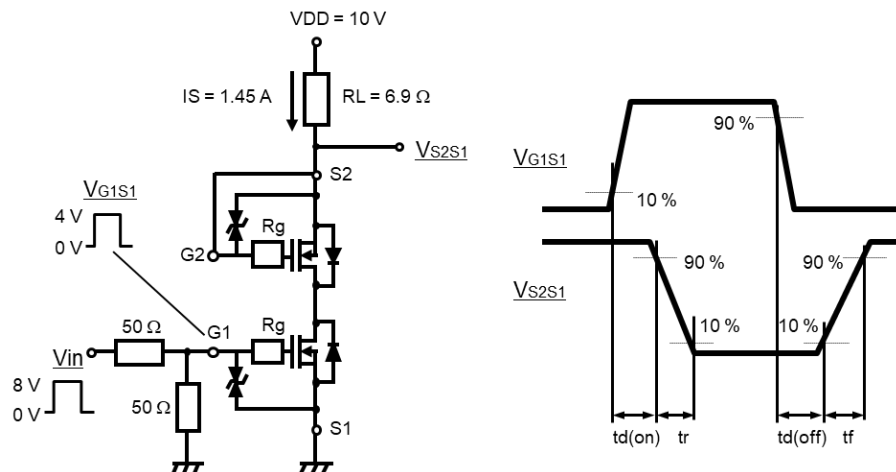
7. ELECTRICAL CHARACTERISTICS Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	20			V	
Zero Gate Voltage Source Current	ISSS	VSS = 20 V, VGS = 0 V			1.0	μA	
Gate-Source Leakage Current	IGSS1	VGS = ±8 V, VSS = 0 V			±1.0	μA	
	IGSS2	VGS = ±3.8 V, VSS = 0 V			±0.1		
Gate-source Threshold Voltage	Vth	IS = 0.1 mA, VSS = 10 V	0.35	0.90	1.40	V	
Source-source On-state Resistance	RSS(on)1	IS = 1.45 A, VGS = 4.5 V	29.0	35.0	45.0	mΩ	
	RSS(on)2	IS = 1.45 A, VGS = 4.1 V	31.0	37.0	48.0		
	RSS(on)3	IS = 1.45 A, VGS = 4.0 V	31.0	37.0	48.0		
	RSS(on)4	IS = 1.45 A, VGS = 3.8 V	31.0	37.5	49.0		
	RSS(on)5	IS = 1.45 A, VGS = 3.7 V	31.5	38.0	50.0		
	RSS(on)6	IS = 1.45 A, VGS = 3.1 V	33.0	42.0	57.0		
	RSS(on)7	IS = 1.45 A, VGS = 2.5 V	34.0	64.0	100		
Body Diode Forward Voltage	VF(s-s)	IF = 1.45 A, VGS = 0 V		0.8	1.2	V	
Input Capacitance *1	Ciss	VSS = 10 V, VGS = 0 V, f = 1 kHz		440		pF	
Output Capacitance *1	Coss			82			
Reverse Transfer Capacitance *1	Crss			68			
Turn-on Delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4 V IS = 1.45 A		0.12		μs	
Rise Time *1,*2	tr			0.26			
Turn-off Delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4 to 0 V IS = 1.45 A		0.54		μs	
Fall Time *1,*2	tf			0.39			
Total Gate Charge *1	Qg	VDD = 10 V		4.5		nC	
Gate-source Charge *1	Qgs		VGS = 0 to 4 V		1.1		
Gate-drain Charge *1	Qgd		IS = 2.9 A		1.2		

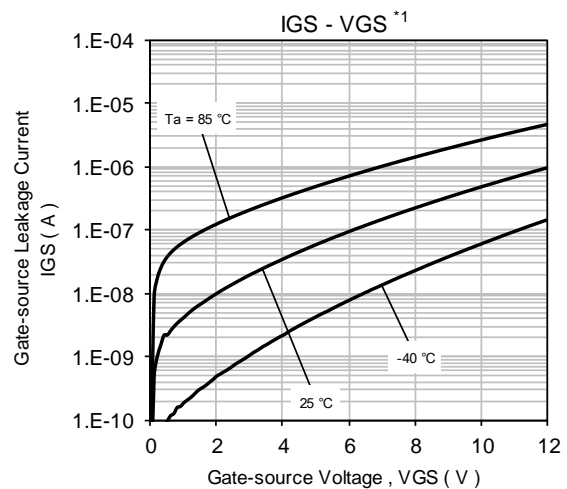
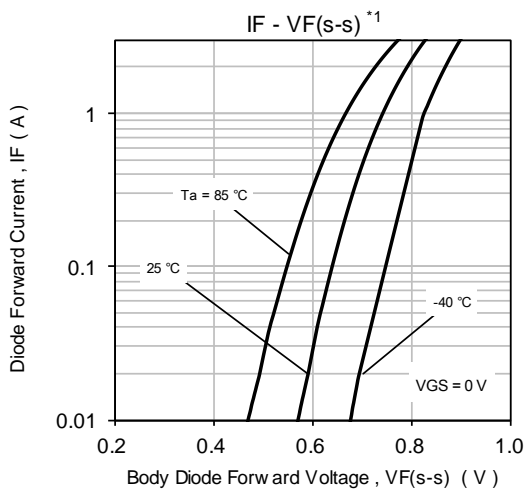
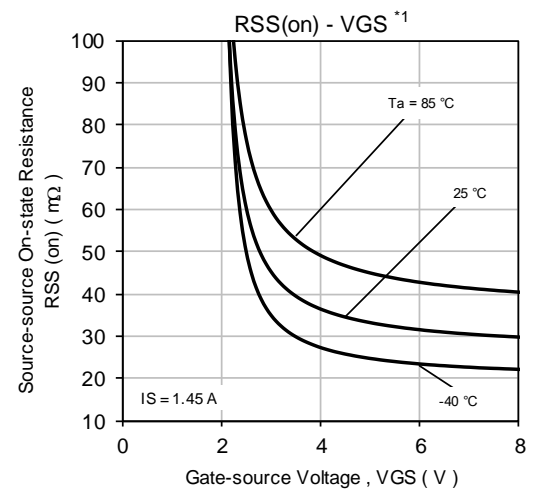
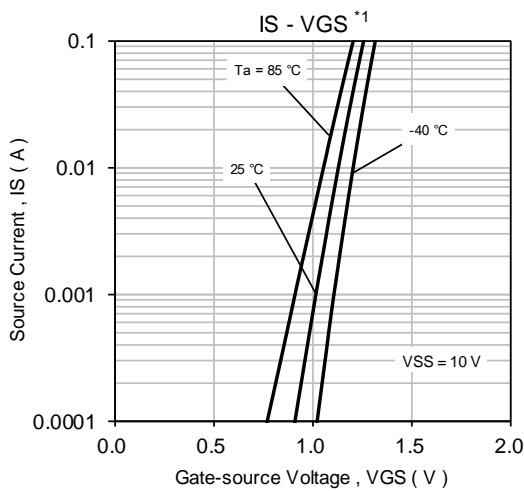
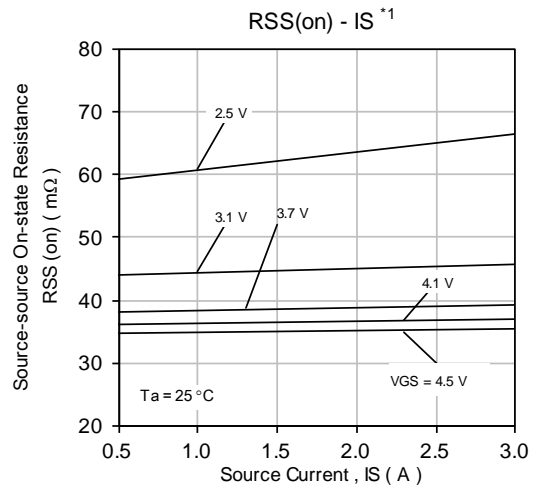
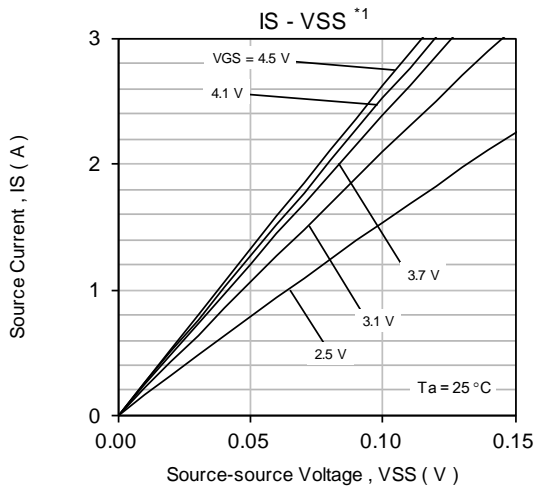
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Guaranteed by design, not subject to production testing

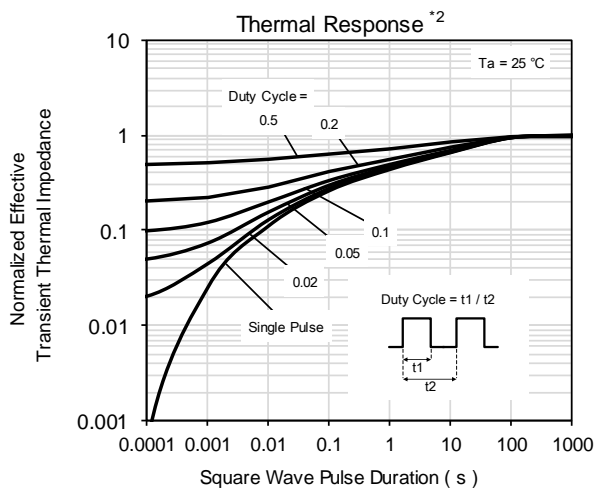
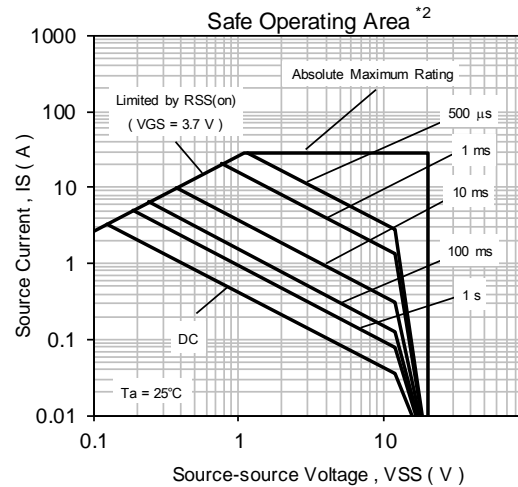
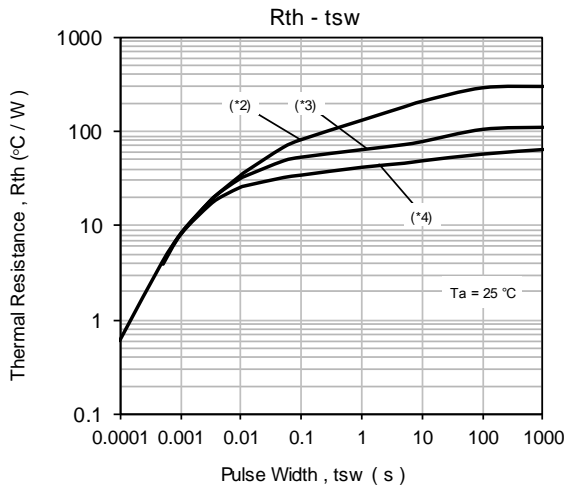
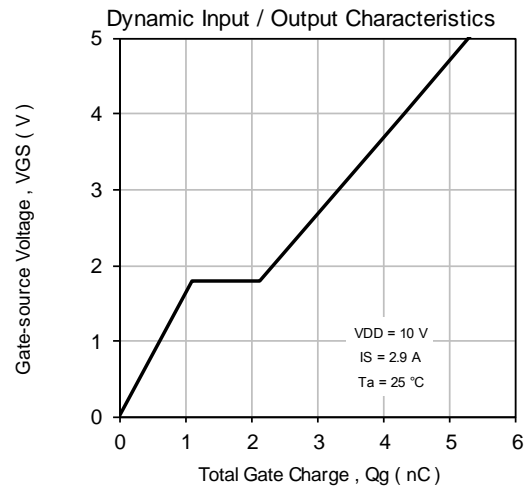
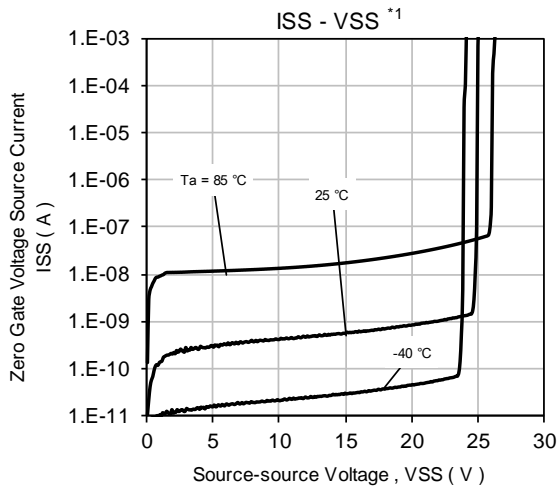
\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



8. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)

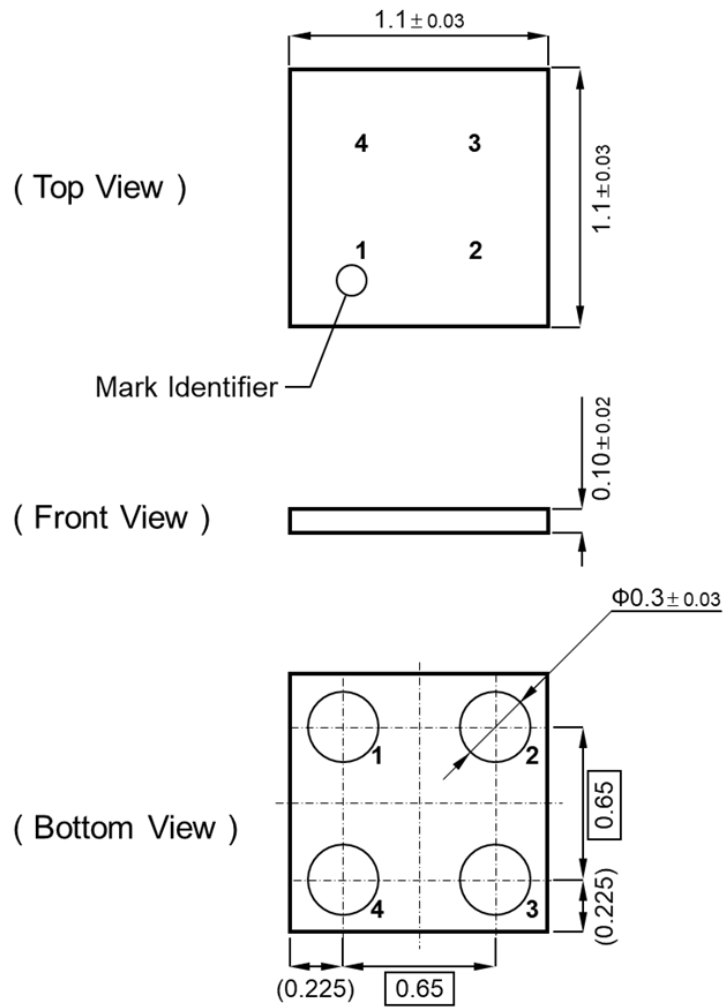


Note

- \*1 Pulse measurement.
- \*2 Mounted on FR4 board (25.4 mm × 25.4 mm × t1.0 mm). FR4 board partially covered with copper pad (18 mm<sup>2</sup> area, 36  $\mu\text{m}$  thickness).
- \*3 Mounted on FR4 board (25.4 mm × 25.4 mm × t1.0 mm). FR4 board fully covered with copper pad (608 mm<sup>2</sup> area, 36  $\mu\text{m}$  thickness).
- \*4 Mounted on ceramic board (70 mm × 70 mm × t1.0 mm).

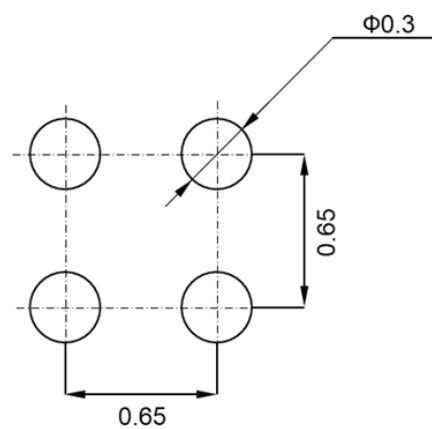
9. OUTLINE

Unit : mm



10. Land & Stencil Pattern ( reference )

Unit : mm



11. REVISION HISTORY

Date	Revision	Description
2021.2.5	1.00	1. initially issued.

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